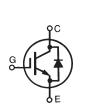


Preliminary Technical Information

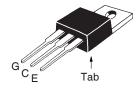
High-Gain IGBT w/ Diode

IXGP30N60B4D1

High-Speed PT Trench IGBT







G = Gate	C = Collector
E = Emitter	Tab = Collector

Features

- Optimized for Low Conduction and Switching Losses
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- International Standard Package

Advantages

- High Power Density
- Low Gate Drive Requirement

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- DC Choppers
- AC Motor Speed Drives
- DC Servo and Robot Drives
- PFC Circuits

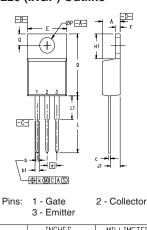
Symbol	Test Conditions	Maximum Ratings		
V _{ces}	T_ = 25°C to 150°C	600	V	
	$T_{J} = 25^{\circ}C$ to 150°C, $R_{GE} = 1M\Omega$	600	V	
V _{GES}	Continuous	±20	V	
V _{GEM}	Transient	±30	V	
I _{C25}	$T_c = 25^{\circ}C$	56	A	
I _{C110}	$T_{c} = 110^{\circ}C$	30	A	
I _{F110}	$T_{c}^{\circ} = 110^{\circ}C$	10	A	
I _{CM}	$T_c = 25^{\circ}C$, 1ms	156	A	
SSOA	$V_{ge} = 15V, T_{yj} = 125^{\circ}C, R_{g} = 10\Omega$	I _{CM} = 48	A	
(RBSOA)	Clamped Inductive Load	$@\leq V_{ces}$		
P _c	$T_c = 25^{\circ}C$	190	W	
T,		-55 +150	°C	
T _{JM}		150	°C	
T _{stg}		-55 +150	°C	
T	Maximum Lead Temperature for Soldering	300	°C	
	1.6 mm (0.062in.) from Case for 10s	260	°C	
M _d	Mounting Torque	1.13/10	Nm/lb.in.	
Weight		3	g	
-				

Symbol (T _J = 25°C, U	cteristic Typ.	Values Max.			
V _{GE(th)}	I_{c} = 250 μ A, V_{ce} = V_{ge}	4.0		6.5	V
I _{ces}	$V_{CE} = V_{CES}, V_{GE} = 0V$			10	μA
	$T_{J} = 125^{\circ}C$			500	μA
I _{ges}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
V _{CE(sat)}	I _c = 24A, V _{ge} = 15V, Note 1		1.5	1.7	V
. /	T_ = 125°C		1.5		V

LIXYS										
Symbol Test Conditions Characteristic Values										
(T _J = 25	5°C Ur	nless Otherwise Specified)	Тур.	Max.						
g _{fs}		$I_{c} = 24A, V_{ce} = 10V, Note 1$	10	17	S					
C _{ies})			860	pF					
C _{oes}	}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		70	pF					
C _{res}	J			29	pF					
Qg)			77	nC					
Q _{ge}	}	$I_{c} = 24A, V_{GE} = 15V, V_{CE} = 0.5 \bullet V_{CES}$		9	nC					
Q _{gc}	J			33	nC					
t _{d(on)})			21	ns					
t _{ri}		Inductive Load, T ₁ = 25°C		34	ns					
E _{on}		$I_{c} = 24A, V_{GE} = 15V$		0.44	mJ					
t _{d(off)}	$\left(\right)$	$V_{CF} = 400V, R_{G} = 10\Omega$		200	ns					
t _{fi}		Note 2		88	ns					
E _{off}	J			0.70	1.30 mJ					
t _{d(on)}				20	ns					
t _{ri}		Inductive Load, T _J = 125°C		33	ns					
Eon		I _c = 24A, V _{GE} = 15V		0.75	mJ					
t _{d(off)}	($V_{ce} = 400V, R_{g} = 10\Omega$		288	ns					
t _{fi}		Note 2		223	ns					
E _{off}	J			1.50	mJ					
R _{thJC}					0.66 °C/W					
R _{thCS}				0.50	°C/W					

IXGP30N60B4D1

TO-220 (IXGP) Outline



SYM	INCH	IES	MILLIMETERS		
3114	MIN	MAX	MIN	MAX	
A	.170	.190	4.32	4.83	
b	.025	.040	0.64	1.02	
b1	.045	.065	1.15	1.65	
С	.014	.022	0.35	0.56	
D	.580	.630	14.73	16.00	
E	.390	.420	9.91	10.66	
е	.100 BSC		2.54 BSC		
F	.045	.055	1.14	1.40	
H1	.230	.270	5.85	6.85	
J1	.090	.110	2.29	2.79	
k	0	.015	0	0.38	
L	.500	.550	12.70	13.97	
L1	.110	.230	2.79	5.84	
ØР	.139	.161	3.53	4.08	
Q	.100	.125	2.54	3.18	

Reverse Diode (FRED)

SymbolTest ConditionsChara(T_j = 25°C, Unless Otherwise Specified)Min.					Value: Max.	
V _F		$I_{_{\rm F}}$ = 10A, $V_{_{ m GE}}$ = 0V, Note 1 $T_{_{ m J}}$ = 150°C			2.66 1.66	
I _{RM})	$I_{\rm F} = 12A, V_{\rm GE} = 0V,$		2.5		A
t _{rr}	J	$-di_{F}/dt = 100A/\mu s, V_{R} = 100V, T_{J} = 125^{\circ}C$		110		ns
t _{rr}		$I_{_{\rm F}}=1\text{A},V_{_{\rm GE}}=0\text{V},\text{-di}_{_{\rm F}}/\text{dt}=100\text{A}/\mu\text{s},V_{_{\rm R}}=30\text{V}$		30		ns
$\mathbf{R}_{_{\mathrm{thJC}}}$					2.5	°C/W

Notes:

- 1. Pulse test, t \leq 300µs, duty cycle, d \leq 2%.
- 2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_g.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves th	e Riaht to	Change Limits	. Test Conditions	, and Dimensions.

IXYS MOSFETs and IGBTs are covered	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
by one or more of the following U.S. patents:	4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	